

Title (en)

A METHOD FOR MAKING COMPOSITE SPUTTERING TARGETS AND THE TARGETS MADE IN ACCORDANCE WITH THE METHOD

Title (de)

VERFAHREN ZUR HERSTELLUNG VON VERBUNDSTOFF-SPUTTER-TARGETS UND GEMÄSS DEM VERFAHREN HERGESTELLTE TARGETS

Title (fr)

PROCÉDÉ POUR FABRIQUER DES CIBLES DE PULVÉRISATION CATHODIQUE COMPOSITES ET CIBLES FABRIQUÉES SELON LE PROCÉDÉ

Publication

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Application

**EP 09723334 A 20090129**

Priority

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Abstract (en)

[origin: WO2009117043A1] Composite sputtering targets are made by hot pressing metal or metal containing powders into a backing plate which can be comprised of a different material with a depression formed in a surface or can be a used sputtering target of the same or different material. The depression corresponds to the erosion pattern of a target having the same geometry. The depression can be formed for example, by machining. The backing plate is loaded into a graphite die and covered with the sputtering material to form an assembly. A ram is added and the assembly with the ram is loaded into a hot press which is taken to an appropriate pressure and temperature under vacuum to form a composite sputtering target having a sputtering zone of densified sputtering material.

IPC 8 full level

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Citation (search report)

See references of WO 2009117043A1

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